

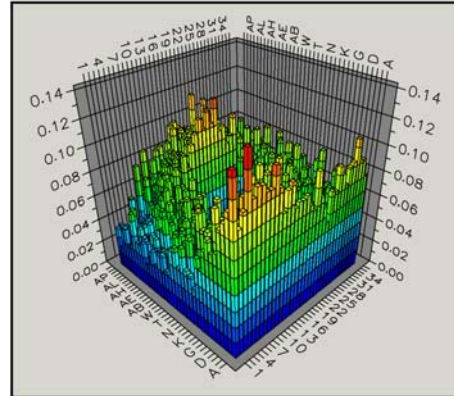
## UltraVim Plus Technology

The UltraVim Plus inspection systems are designed to meet the needs of semiconductor device manufacturers and other OEM equipment suppliers for comprehensive package inspection. Built on patented technology, our systems offer a proven solution for the inspection of semiconductor packages.



- **UltraVim and UltraVim Plus**

The UltraVim and UltraVim Plus vision inspection modules use high resolution digital cameras, precision telecentric optics, and patented vision technology to measure and inspect leads and balls of most packages in three dimensions. Standard device file libraries provide for easy setup and training with multiple reporting and language options.



- **UltraMark**

The UltraMark system provides high speed ink and laser mark inspection. Users can select tolerances for correlation, contrast, position and rotation. Multiple search windows can be used to define characters as logos or pin1 identification marks.

- **Ultra2D**

The new Ultra2D system provides high speed, low cost alignment and pattern matching inspection solutions using FireWire machine vision cameras and your computer hardware without the expense of an additional PC, vision appliance or frame grabber board.



**For more information or a quotation, please contact us:**

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